

2SA715

Silicon PNP Epitaxial

HITACHI

Application

Low frequency power amplifier complementary pair with 2SC1162

Outline

TO-126 MOD



1. Emitter
2. Collector
3. Base

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Item	Symbol	Rating	Unit
Collector to base voltage	V_{CBO}	-35	V
Collector to emitter voltage	V_{CEO}	-35	V
Emitter to base voltage	V_{EBO}	-5	V
Collector current	I_{C}	-2.5	A
Collector peak current	$I_{\text{C(peak)}}$	-3	A
Collector power dissipation	P_{C}	0.75	W
	P_{C}^{*1}	10	W
Junction temperature	T_{j}	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

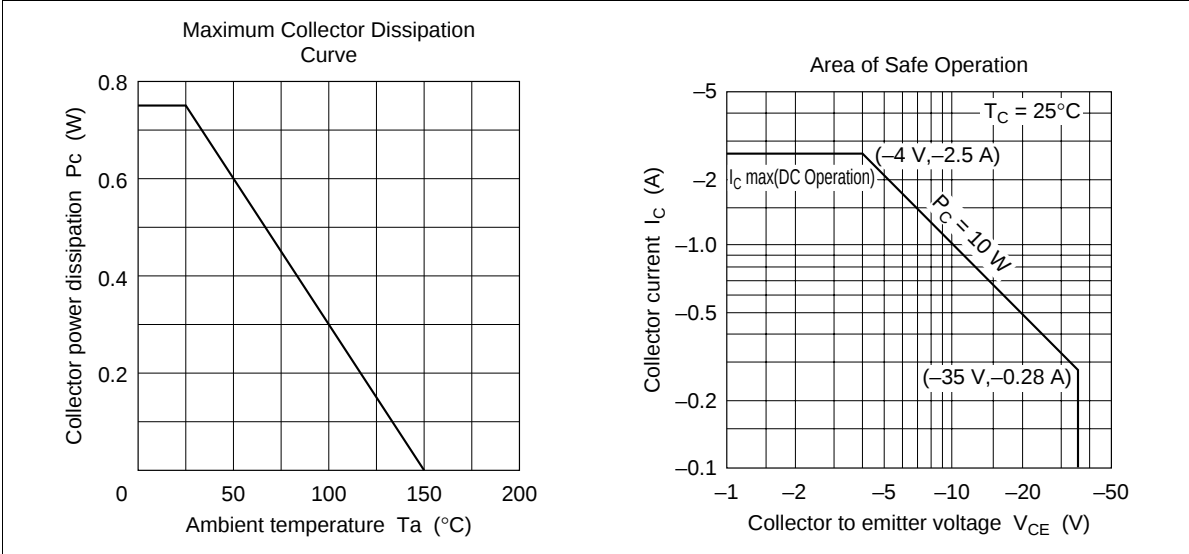
Note: 1. Value at $T_{\text{C}} = 25^\circ\text{C}$

Electrical Characteristics (Ta = 25°C)

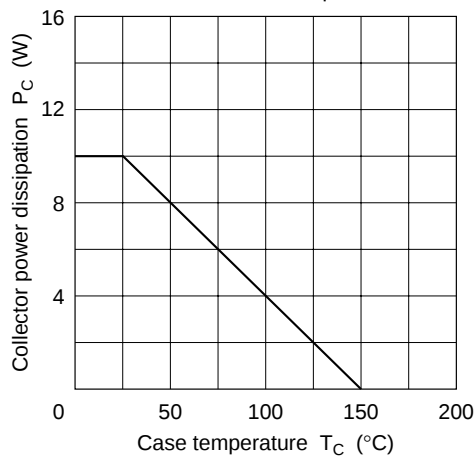
Item	Symbol	Min	Typ	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-35	—	—	V	$I_C = -1\text{ mA}$, $I_E = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-35	—	—	V	$I_C = -10\text{ mA}$, $R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	-5	—	—	V	$I_E = -1\text{ mA}$, $I_C = 0$
Collector cutoff current	I_{CBO}	—	—	-20	μA	$V_{CB} = -35\text{ V}$, $I_E = 0$
DC current transfer ratio	h_{FE}^{*1}	60	—	320		$V_{CE} = -2\text{ V}$, $I_C = -0.5\text{ A}$
	h_{FE}	20	—	—		$V_{CE} = -2\text{ V}$, $I_C = -1.5\text{ A}$ (Pulse test)
Base to emitter voltage	V_{BE}	—	-1.0	-1.5	V	$V_{CE} = -2\text{ V}$, $I_C = -1.5\text{ A}$ (Pulse test)
Collector to emitter saturation voltage	$V_{CE(sat)}$	—	-0.5	-1.0	V	$I_C = -2\text{ A}$, $I_B = -0.2\text{ A}$ (Pulse test)
Gain bandwidth product	f_T	—	160	—	MHz	$V_{CE} = -2\text{ V}$, $I_C = -0.2\text{ A}$ (Pulse test)

Note: 1. The 2SA715 is grouped by h_{FE} as follows.

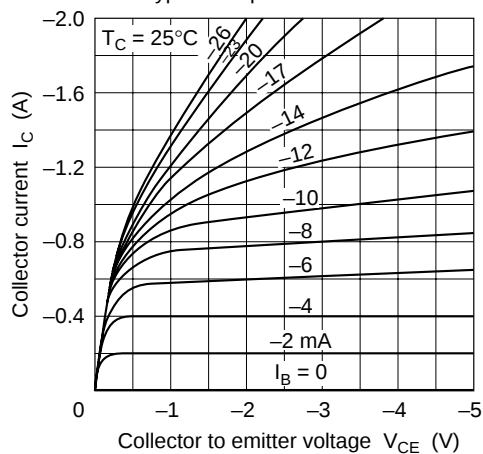
B	C	D
60 to 120	100 to 200	160 to 320



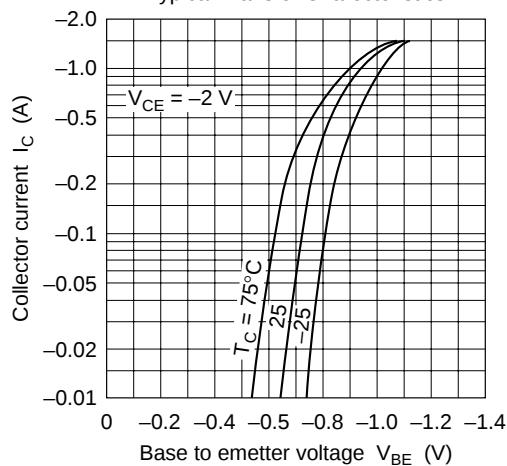
Maximum Collector Dissipation Curve



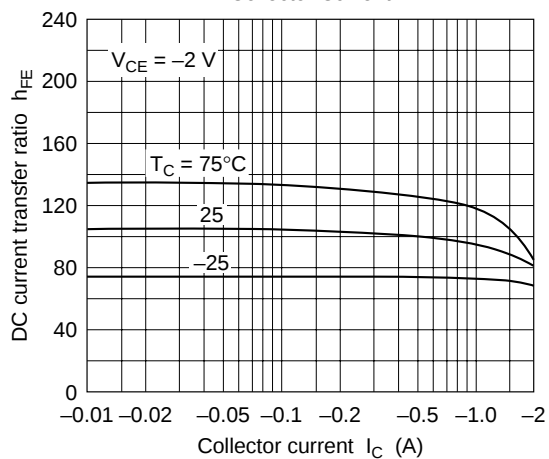
Typical Output Characteristics

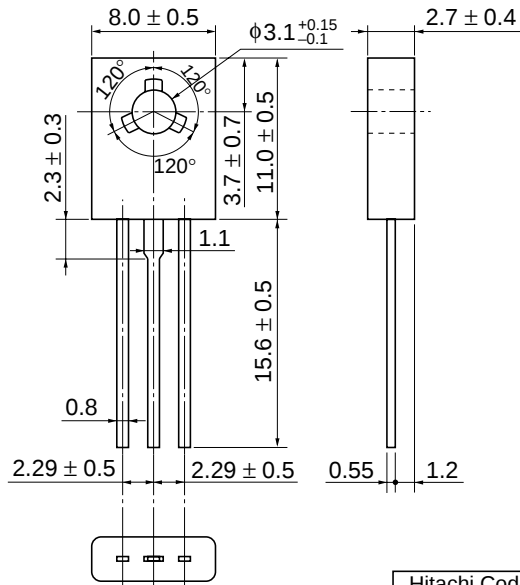


Typical Transfer Characteristics



DC Current Transfer Ratio vs. Collector Current





Hitachi Code	TO-126 Mod
JEDEC	—
EIAJ	—
Weight (reference value)	0.67 g

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